

SN 10/068,814
Page 2

AMENDMENTS AND LISTING OF CLAIMS

1. (Currently Amended) A head suspension or head suspension component for use in supporting a read/write head in a storage device, the head suspension or head suspension component comprising a spring region, a flexure and rigid beam region between the spring region and the flexure, wherein the rigid beam region includes an integrated circuit chip that forms a majority of a structural element providing substantial structural support to the head suspension or head suspension component rigid beam region.

2. (Canceled)

3. (Original) The head suspension or head suspension component of claim 2, wherein the chip is electrically connected between the read/write head and externally located electrical components.

4. (Canceled)

5. (Original) The head suspension or head suspension component of claim 4, wherein the load beam comprises a first portion and a second portion, with the first portion coupled to one end of the chip and the second portion coupled to an opposite end of the chip.

6. (Original) The head suspension or head suspension component of claim 5, wherein the first portion comprises a mounting region and a spring region.

7-10. (Canceled)

11. (Original) The head suspension or head suspension component of claim 4, further comprising a flexure and wherein the flexure mounts to the chip.

12. (Original) The head suspension or head suspension component of claim 1, further comprising at least one electrical trace electrically coupled to the chip.

13. (Canceled)

SN 10/068,814
Page 3

14. (Original) The head suspension or head suspension component of claim 1, wherein the chip comprises a gimballing dimple.

15. (Original) The head suspension or head suspension component of claim 1, wherein the chip contacts a gimballing dimple.

16. (Original) The head suspension or head suspension component of claim 1, wherein the chip comprises a head lift limiter.

17. (Currently Amended) The head suspension or head suspension component of claim 1, wherein the chip is a stiffening member extending lengthwise at least half of that provides substantial stiffness to the length between the spring region and flexure head suspension or head suspension component.

18. (Canceled)

19. (Currently Amended) The head suspension or head suspension component of claim 18, wherein the chip is externally shaped to have comprises an aerodynamic cross-sectional profile aerodynamically configured to reduce vibration of the head suspension or head suspension component.

20. (Currently Amended) The head suspension or head suspension component of claim 18, wherein the chip shape comprises a cross-section profile aerodynamically configured to reduce means for minimizing wind drag of the head suspension or head suspension component.

21. (Previously presented) The head suspension or head suspension component of claim 1, wherein the chip comprises an external surface configured as a heat dissipation structure.

22. (Canceled)

SN 10/068,814

Page 4

23. (Previously presented) The head suspension or head suspension component of claim 1, wherein the chip comprises engaging structure configured to mechanically engage with a head suspension component.

24. (Canceled)

25. (Previously presented) The head suspension or head suspension component of claim 23, wherein the engaging structure comprises at least one of holes, slots, depressions, indentations and grooves.

26. (Previously presented) The head suspension or head suspension component of claim 23, wherein the engaging structure is externally protruding from the chip.

27. (Original) The head suspension or head suspension component of claim 26, wherein the externally protruding structure comprises at least one of tabs, rails, rods, posts, knobs, loops and resonance whiskers.

28. (Original) The head suspension or head suspension component of claim 1, wherein the chip is welded to a head suspension component.

29. (Original) The head suspension or head suspension component of claim 1, wherein the chip is adhered to a head suspension component.

30. (Original) The head suspension or head suspension component of claim 1, wherein the chip is mechanically fastened to a head suspension component.

31. (Original) The head suspension or head suspension component of claim 1, further comprising a MEMS device and wherein the chip is coupled to the MEMS device.

32. (Original) The head suspension or head suspension component of claim 1, wherein the chip comprises a head lift component.

33. (Previously presented) The head suspension or head suspension component of claim 32, wherein the head lift component is integrally formed from the chip material.

SN 10/068,814
Page 5

34. (Original) The head suspension or head suspension component of claim 32, wherein the head lift component is attached to the chip.

35-40. (Canceled)

41. (New) A head suspension or head suspension component for supporting a read/write head in a storage device, the head suspension or head suspension component comprising a loadbeam and a flexure the loadbeam having a rigid region, which comprises an integrated circuit chip mounted to and forming a majority of the rigid region.

42. (New) The head suspension or head suspension component of claim 41, wherein the chip forms at least three fourth of the rigid region.

43. (New) The head suspension or head suspension component of claim 41, wherein the rigid region has a length and width, and the chip occupies at least half of the length of the rigid region and at least half of the width of the rigid region.

44. (New) The head suspension or head suspension component of claim 41, wherein the chip has a flat shape with a top major surface and bottom major surface, wherein both top and bottom major surfaces are exposed to the ambient.

45. (New) The head suspension or head suspension component of claim 44, wherein the head suspension or head suspension component has a flat shape with a major top surface and major bottom surface, wherein the major top surface of the chip is exposed to the ambient above the major top surface of the head suspension or head suspension component, and the major bottom surface of the chip is exposed to the ambient below the major bottom surface of the head suspension or head suspension component.

46. (New) The head suspension or head suspension component of claim 45, wherein at least one of the top and bottom major surfaces of the chip is bonded to a base.

SN 10/068,814
Page 6

47. (New) The head suspension or head suspension component of claim 41, wherein the chip comprises an electrical circuitry and means for controlling wind-induced vibrations of the head suspension or head suspension component.

48. (New) A head suspension or head suspension component for supporting a read/write head in a storage device, the head suspension or head suspension component comprising a loadbeam and a flexure. the loadbeam having a rigid region, a majority of the rigid region having an elastic modulus of at least 3.9×10^8 mN/mm².